SDLS152 – DECEMBER 1972 – REVISED MARCH 1988

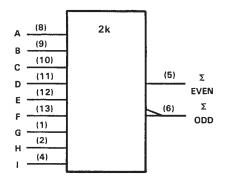
- Generates Either Odd or Even Parity for Nine Data Lines
- Cascadable for n-Bits
- Can Be Used to Upgrade Existing Systems using MSI Parity Circuits
- Typical Data-to-Output Delay of Only 14 ns for 'S280 and 33 ns for 'LS280
- Typical Power Dissipation: 'LS280 . . . 80 mW 'S280 . . . 335 mW

FUNCTION TABLE

NUMBER OF INPUTS A	OUTP	UTS
THRU I THAT ARE HIGH	Σ ΕVΕΝ	Σ ODD
0, 2, 4, 6, 8	н	L
1, 3, 5, 7, 9	L	н

H = high level, L = low level

logic symbol[†]



[†]This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

description

These universal, monolithic, nine-bit parity generators/checkers utilize Schottky-clamped TTL high-performance circuitry and feature odd/even outputs to faciliate operation of either odd or even parity application. The word-length capability is easily expanded by cascading as shown under typical application data.

Series 54LS/74LS and Series 54S/74S parity generators/checkers offer the designer a trade-off between reduced power consumption and high performance. These devices can be used to upgrade the performance of most systems utilizing the '180 parity generator/checker. Although the 'LS280 and 'S280 are implemented without expander inputs, the corresponding function is provided by the availability of an input at pin 4 and the absence of any internal connection at pin 3. This permits the 'LS280 and 'S280 to be substituted for the '180 in existing designs to produce an identical function even if 'LS280's and 'S280's are mixed with existing '180's.

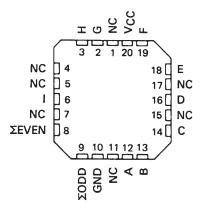
These devices are fully compatible with most other TTL circuits. All 'LS280 and 'S280 inputs are buffered to lower the drive requirements to one Series 54LS/74LS or Series 54S/74S standard load, respectively.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



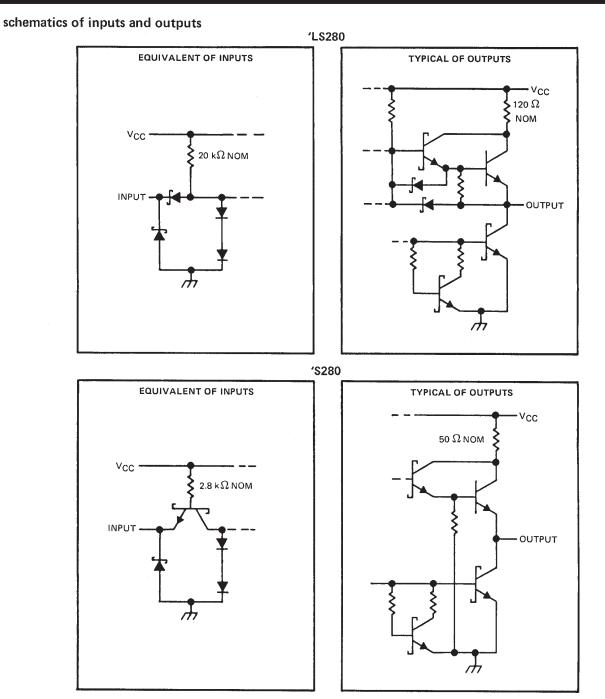
140 VCC $G \square 1$ $H \square 2$ 13 F 120 E 1 04 11D D ΣEVEN 5 10 C $\Sigma ODD \square 6$ 9 B GND Г 8 Α

SN54LS280, SN54S280 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage (see Note 1)	
Input voltage: 'LS280	
'S280	
Operating free-air temperature range: SN54'	
SN74'	0° C to 70° C
Storage temperature range	
NOTE 1: Voltage values are with respect to network ground terminal.	

N sp g d terminal.



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recommended operating conditions

		SI	N54LS2	80	SN74LS280			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage	2			2	· · · · · ·		V
VIL	Low-level input voltage			0.7			0.8	V
юн	High-level output current			- 0.4			- 0.4	mA
^I OL	Low-level output current			4		· · · · · · · · · · · · · · · · · · ·	8	mA
TA	Operating free-air temperature	- 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDIT	TIONS	SI	N54LS2	80	S	N74LS2	80	
		TEST CONDI	10145	MIN	түр‡	MAX	MIN	TYP‡	MAX	UNIT
VIK	$V_{CC} = MIN,$	l _l = – 18 mA				1.5			- 1.5	V
V _{OH}	V _{CC} = MIN, V _{IL} = MAX,	V _{IH} = 2 V, I _{OH} = 0.4 m	A	2.5	3.4		2.7	3.4		v
VOL	V _{CC} = MIN, V _{IL} = MAX	V _{IH} = 2 V,	I _{OL} = 4 mA I _{OL} = 8 mA		0.25	0.4		0.25	0.4	v
Ц	V _{CC} = MAX,	V1 = 7 V				0.1			0.1	mA
IН	V _{CC} = MAX,	VI = 2.7 V	· · · ·			20		*	20	μA
ЦĻ	V _{CC} = MAX,	VI = 0.4 V				- 0.4			- 0.4	mA
los§	V _{CC} = MAX			- 20		- 100	- 20		- 100	mA
lcc	V _{CC} = MAX,	See Note 2			16	27		16	27	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡] All typical values are at V_{CC} = 5 V, $T_A = 25^{\circ}$ C. §Not more than one output should be shorted at a time and duration of the short circuit should not exceed one second.

NOTE 2: I_{CC} is measured with all inputs grounded and all outputs open.

switching characteristics, V_{CC} = 5 V, T_A = 25° C

PARAMETER¶	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	түр	MAX	UNIT
^t PLH	Data	Σ Even			33	50	
^t PHL	0818	2 Even	$C_L = 15 \text{ pF}, R_L = 2 \text{ k}\Omega,$ Inputs not under test at 0 V.		29	45	ns
^t PLH	Data	Σ Odd	See Note 3		23	35	
^t PHL	Data	2 Odu	See Note S		31	50	ns

¶ tp_H = propagation delay time, low-to-high-level output; tpHL = propagation delay time, high-to-low-level output NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



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recommended operating conditions

	S	N54S28	30	S			
	MIN	MIN NOM MAX MIN			NOM	MAX	UNIT
Supply voltage, V _{CC}	4.5	5	5.5	4.75	5	5.25	V
High-level output current, IOH			-1			-1	mA
Low-level output current, IOL			20			20	mA
Operating free-air temperature, T _A	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CONDITION	s†	MIN	TYP‡	MAX	UNIT
ЧΗ	High-level input voltage			2			V
VIL	Low-level input voltage				·····	0.8	V
VIK	Input clamp voltage	$V_{CC} = MIN, I_I = -18 \text{ mA}$				1.2	V
Хон	High-level output voltage	$V_{CC} = MIN, V_{IH} = 2V,$	SN54S'	2.5	3.4		
· OH		VIL = 0.8 V, IOH = -1 mA	SN74S'	2.7	3,4		V
Vol	Low-level output voltage	$V_{CC} = MIN, V_{IH} = 2 V,$				0.5	V
- OL		VIL = 0.8 V, IOL = 20 mA				0.5	
II.	Input current at maximum input voltage	V _{CC} = MAX, V _I = 5.5 V				1	mA
ŧн	High-level input current	V _{CC} = MAX, V ₁ = 2.7 V				50	μA
ΊL	Low-level input current	V _{CC} = MAX, V _I = 0.5 V	and and an an an and an			-2	mA
los	Short-circuit output current§	V _{CC} = MAX		-40		-100	mA
		Vee - MAX See New 2	SN54S280		67	99	
Icc	Supply current	V _{CC} = MAX, See Note 2	SN74S280		67	105	mA
		$V_{CC} = MAX, T_A = 125^{\circ}C,$ See Note 2	SN54S280N			94	mA

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡]All typical values are at $V_{CC} = 5 V$, $T_A = 25^{\circ}C$.

Not more than one output should be shorted at a time and duration of the short circuit should not exceed one second.

NOTE 2: ICC is measured with all inputs grounded and all outputs open.

switching characteristics, V_{CC} = 5 V, T_A = 25° C

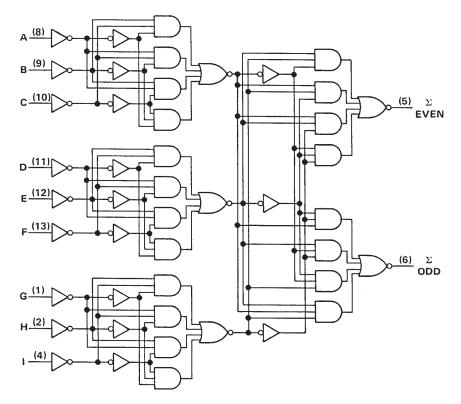
PARAMETER¶	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	ТҮР	MAX	UNIT
^t PLH	Data	Σ Even			14	21	
^t PHL	Data	2 Even	$C_{L} = 15 pF, R_{L} = 280 \Omega,$		11.5	18	ns
^t PLH	Data	Σ Odd	See Note 3		14	21	
tPHL	Data	2.000			11.5	18	ns

 \P_{tpLH} = propagation delay time, low-to-high-level output: t_{PHL} = propagation delay time, high-to-low-level output NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



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logic diagram (positive logic)

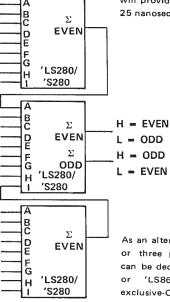


Pin numbers shown are for D, J, N, and W packages.

TYPICAL APPLICATION DATA

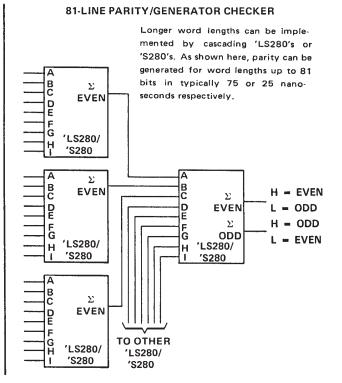
25-LINE PARITY/GENERATOR CHECKER

Three 'LS280's or 'S280's can be used to implement a 25-line parity generator/checker. This arrangement will provide parity in typically 75 or 25 nanoseconds respectively.



will provide parity in typically 75 o 25 nanoseconds respectively.

As an alternative, the outputs of two or three parity generators/checkers can be decoded with a 2-input ('S86 or 'LS86) or 3-input ('S135) exclusive-OR gate for 18- or 27-line parity applications.





17-May-2014

PACKAGING INFORMATION

Orderable Device		Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)					(2)	(6)	(3)		(4/5)	
JM38510/32901B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 32901B2A	Samples
JM38510/32901BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32901BCA	Samples
JM38510/32901BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32901BCA	Samples
JM38510/32901BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32901BDA	Samples
JM38510/32901BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32901BDA	Samples
M38510/32901B2A	ACTIVE	LCCC	FK	20		TBD	Call TI	Call TI	-55 to 125		Samples
M38510/32901B2A	ACTIVE	LCCC	FK	20		TBD	Call TI	Call TI	-55 to 125		Samples
M38510/32901BCA	ACTIVE	CDIP	J	14		TBD	Call TI	Call TI	-55 to 125		Samples
M38510/32901BCA	ACTIVE	CDIP	J	14		TBD	Call TI	Call TI	-55 to 125		Samples
M38510/32901BDA	ACTIVE	CFP	W	14		TBD	Call TI	Call TI	-55 to 125		Samples
M38510/32901BDA	ACTIVE	CFP	W	14		TBD	Call TI	Call TI	-55 to 125		Samples
SN54LS280J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS280J	Samples
SN54LS280J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS280J	Samples
SN54S280J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54S280J	Samples
SN54S280J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54S280J	Samples
SN74LS280D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS280	Samples
SN74LS280D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS280	Samples
SN74LS280DE4	ACTIVE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70		Samples
SN74LS280DE4	ACTIVE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70		Samples



PACKAGE OPTION ADDENDUM

17-May-2014

Orderable Device		Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Sample
	(1)				Qty	(2)	(6)	(3)		(4/5)	
SN74LS280DG4	ACTIVE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70		Sampl
SN74LS280DG4	ACTIVE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70		Sampl
SN74LS280J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	0 to 70		
SN74LS280J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	0 to 70		
SN74LS280N	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS280N	Sampl
SN74LS280N	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS280N	Samp
SN74LS280N3	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI	0 to 70		
SN74LS280N3	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI	0 to 70		
SN74LS280NE4	ACTIVE	PDIP	Ν	14		TBD	Call TI	Call TI	0 to 70		Sampl
SN74LS280NE4	ACTIVE	PDIP	Ν	14		TBD	Call TI	Call TI	0 to 70		Samp
SN74LS280NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS280	Samp
SN74LS280NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS280	Samp
SN74LS280NSRE4	ACTIVE	SO	NS	14		TBD	Call TI	Call TI	0 to 70		Samp
SN74LS280NSRE4	ACTIVE	SO	NS	14		TBD	Call TI	Call TI	0 to 70		Samp
SN74LS280NSRG4	ACTIVE	SO	NS	14		TBD	Call TI	Call TI	0 to 70		Samp
SN74LS280NSRG4	ACTIVE	SO	NS	14		TBD	Call TI	Call TI	0 to 70		Samp
SN74S280D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70		
SN74S280D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70		
SN74S280N	NRND	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74S280N	
SN74S280N	NRND	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74S280N	
SN74S280N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74S280N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74S280NE4	NRND	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		



PACKAGE OPTION ADDENDUM

17-May-2014

Orderable Device	Status	Package Type		Pins		Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SN74S280NE4	NRND	PDIP	Ν	14		TBD	Call TI	Call TI	0 to 70		
SNJ54LS280FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS 280FK	Samples
SNJ54LS280FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS 280FK	Samples
SNJ54LS280J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS280J	Samples
SNJ54LS280J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS280J	Samples
SNJ54LS280W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS280W	Samples
SNJ54LS280W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS280W	Samples
SNJ54S280FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54S 280FK	Samples
SNJ54S280FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54S 280FK	Samples
SNJ54S280J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54S280J	Samples
SNJ54S280J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54S280J	Samples
SNJ54S280W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54S280W	Samples
SNJ54S280W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54S280W	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die adhesive used between th



PACKAGE OPTION ADDENDUM

17-May-2014

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54LS280, SN54S280, SN74LS280, SN74S280 :

- Catalog: SN74LS280, SN74S280
- Military: SN54LS280, SN54S280

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

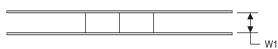
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TAPE AND REEL INFORMATION

REEL DIMENSIONS

TEXAS INSTRUMENTS





TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS280NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

14-Jul-2012



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS280NSR	SO	NS	14	2000	367.0	367.0	38.0

J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14



LEADLESS CERAMIC CHIP CARRIER

FK (S-CQCC-N**) 28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. This package can be hermetically sealed with a metal lid.

D. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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